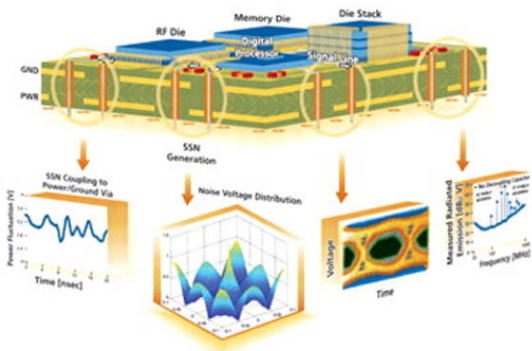


Power Integrity Modeling and Design for Semiconductors and Systems



Madhavan Swaminathan • A. Ege Engin

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POWER INTEGRITY MODELING AND DESIGN FOR SEMICONDUCTORS AND SYSTEMS

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